

June 5, 2002

eTeraView

The e-newsletter of Teradyne's Assembly Test Division

Because Technology Never Stops.

News and Announcements

Teradyne and Sony Collaborate on Unique Cellular Mobile Test Solution

The Assembly Test Division announced the formation of a collaborative partnership with Sony Corporation to develop a unique functional test platform for Sony's range of cellular mobile products. For more information, click here:

http://www.teradyne.com/prods/cbt/news/newsdesk/58news_pr_020520.html

Product Information

Teradyne's Assembly Test Division Announces a New Major Software Upgrade for Optima 7300-Series Automated Optical Inspection (AOI) Systems.

The Assembly Test Division is now introducing another major software upgrade for Optima 7300-Series systems. The C.0. Release adds new features and expands existing functionality. Highlights of the C.0. upgrade includes Board Revision Management, new coverage and stability tools, new production tuning tools, barcode reading enhancements, AOI production reports, Mixed-Board Panel support, and program transportability improvements. For additional information and details features of this upgrade please click here:

http://www.teradyne.com/prods/cbt/products/aoi/7300/7300_sw.html

Recent Technical Papers

"Automatic Inspection of Pin Tips on Backplane Assemblies" by Douglas W. Raymond, Alex Montero and Rickey Buchanan.

Buckling pin shafts on high-density backplanes can be expensive or impossible to repair.

Read how such defects can be detected before the next level of assembly. Click here:

http://www.teradyne.com/prods/cbt/products/library/aoi/autoinsp_test1102.pdf

"Changing Times in Test Strategy Development" by Amit Verma and Paul Hannon

Dramatic new and improved test and inspection options are appearing because of advancements in electronic product complexity and product miniaturization. Click here to read about these options:

http://www.teradyne.com/prods/cbt/products/library/general/changingtime_epp502.pdf

"Inspection Plays a Key Role" by John Arena and Dan Walsh

Board assemblers have invested heavily in technology to detect and repair manufacturing defects.

Modern equipment can discover these failures earlier and measure the variance in the process. This article explores the use of such inspection systems and the statistical foundations that is their operational basic. Click here for more information:

http://www.teradyne.com/prods/cbt/products/library/aoi/inspkey_epp0202.pdf

"Tradeoffs Between Transmission and Cross-Section AXI" by Amit Verma

Read why all potential Automated X-Ray Inspection (AXI) users should carefully consider the impact of technological issues and trade-offs on long-term payback, ease of use, fault coverage and effectiveness of their chosen test strategy. Click here:

http://www.teradyne.com/prods/cbt/products/library/xray/axi_verma-tradeoffs_pce-02.pdf

Upcoming Events

SMT 2002 – SMT Hybrid Packaging Exhibition and Conference, June 18-20, 2002, Nuremberg, Germany.

At this year's exhibit, we will demonstrate how integrated solutions from Teradyne provide flexibility, performance and innovation for the future. Visit Teradyne at Booth #3-214. For more information about our attendance at SMT 2002, click here:

<http://www.teradyne.com/prods/cbt/news/tradeshows/smt2002a.html>

MESA (Manufacturing Enterprise Solutions) Conference and Exposition, June 10-12, 2002, Boston, MA.

Visit Teradyne at Booth #8 where we will feature GR Force/SCE -- a collaborative manufacturing execution system (MES) that provides real-time, high-resolution supply chain and manufacturing information for customers. Click here for more information about MESA:

<http://www.teradyne.com/prods/cbt/news/tradeshows/02mesa.html>

Nepcon East, June 11-12, 2002, Boston, MA

Manual X-Ray and Rework systems along with Teradyne's Design-to-Build software solutions will be on exhibit at booth #2934. For more information, click here:

<http://www.teradyne.com/prods/cbt/news/tradeshows/nepcone02.html>

Optical Communications Test Seminar, June 25, 2002, San Jose, CA

Join us at the Teradyne, San Jose, facility for a free, 4-hour seminar, which includes three focused presentations, a demonstration of Teradyne and Tektronix optical test solutions, and a discussion of your specific test challenges with Teradyne's applications specialists. For more information on the program and to register for the event, click here:

<http://www.teradyne.com/prods/cbt/news/tradeshows/opticalsem.html>

Teradyne Users' Group (TUG) – May, 2003

The TUG 2003 Steering Committee has begun planning the logistics and technical program for the May 5-7, 2003, conference. This conference consists of technical papers, poster sessions, and tutorials that present the latest in Test Technology. TUG remains a very important forum for Teradyne's customers and employees to share technical information. This is an excellent opportunity to share your technical knowledge with leading companies in the electronics industry and to address key issues facing the industry. Any customer that is a licensed user of Teradyne test equipment or software is qualified to join the Users' Group. More details about the event will be forthcoming throughout the year including a call for papers. To keep up-to-date on information about TUG 2003 check out the Teradyne Users' group web site. Click here:

<http://www.teradyne.com/prods/tug/tughome.html>

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